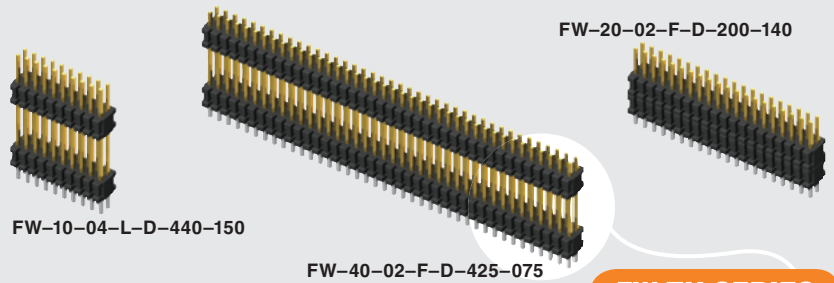




(1,27 mm) .050"



FW-TH SERIES

THROUGH-HOLE MICRO BOARD STACKER

SPECIFICATIONS

For complete specifications see www.samtec.com?FW-TH

Insulator Material: Black Liquid Crystal Polymer
Terminal Material: Phosphor Bronze
Plating: Sn or Au over 50µ" (1,27 µm) Ni
Operating Temp Range: -55°C to +125°C
RoHS Compliant: Yes

Processing: Lead-Free Solderable: Yes

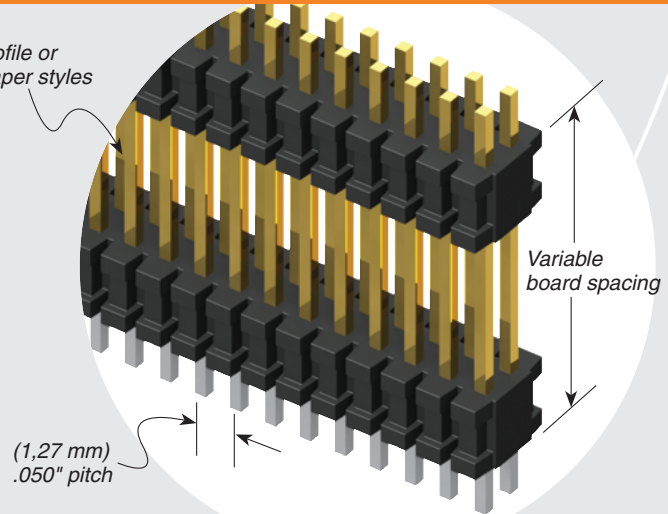
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Mates with: CLP, FFSD, FLE

Low profile or skyscraper styles



ALSO AVAILABLE (MOQ Required)

- Smaller stack heights
- Contact Samtec.

FW	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	D	STACKER HEIGHT	POST HEIGHT	OPTION
	02 thru 50	Specify LEAD STYLE from chart	-F = Gold flash on post, Matte Tin on tail -L = 10µ" (0,25 µm) Gold on post, Matte Tin on tail -G = 10µ" (0,25 µm) Gold on post, Gold flash on tail		-"XXX" = Stacker Height (in inches) Example: -250 = (6,35 mm) .250"	-"XXX" = Post Height (in inches) (1,65 mm) .065" minimum Example: -065 = (1,65 mm) .065"	-ES = End Shroud (-075 post height only. Mates only with CLP.) (5,46 mm) .215" to (15,49 mm) .610" stacker height only, 9 pins/row minimum -EP = End Shroud with Guide Post (-075 post height only. Mates only with CLP.) (5,46 mm) .215" to (15,49 mm) .610" stacker height only, 9 pins/row minimum

LEAD STYLE	TAIL (B)
-01	(1,14) .045
-02	(1,91) .075
-04	(2,29) .090

Technical drawings include:
 - Top view showing pin pitch (1,27) .050 and board spacing (3,42) .135.
 - Side view showing stacker height (5,08) .200 MIN and post height (1,65) .065 MIN.
 - Detail views for options -ES and -EP showing dimensions like (4,76) .188 and (1,91) .075 DIA.

Note: For added mechanical stability, Samtec recommends mechanical board spacers be used in applications with gold or selective gold plated connectors. Contact ipg@samtec.com for more information.

Note: This Series is non-standard, non-returnable.